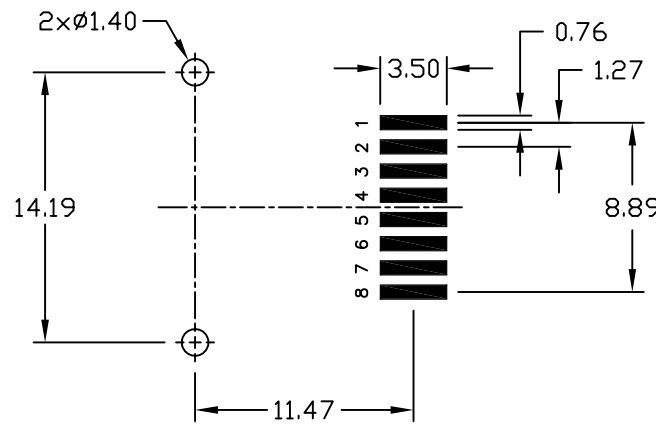
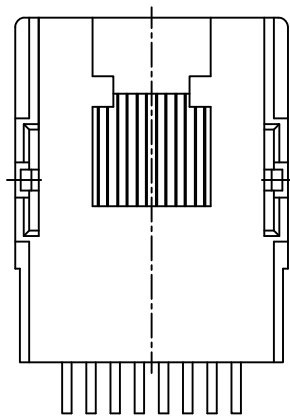
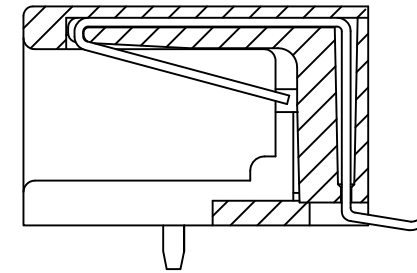
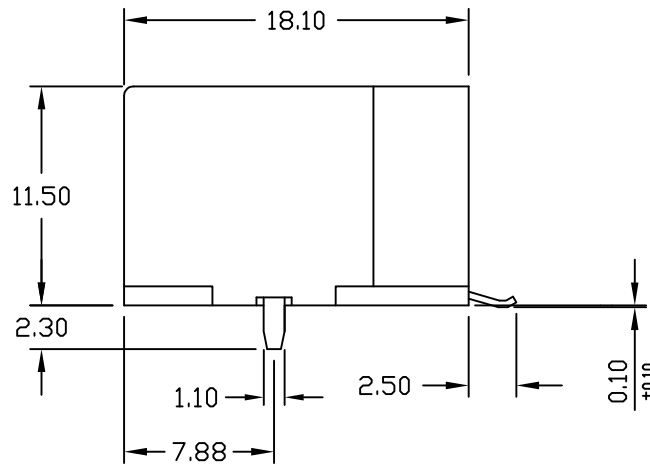
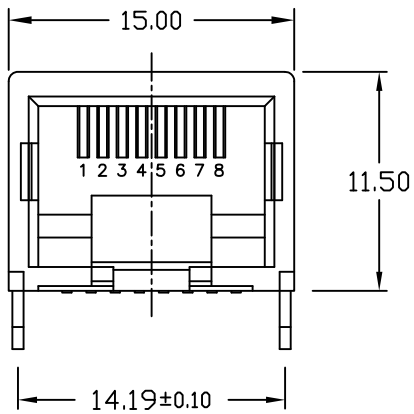


REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
A		NEW	21.05.2000	KATHY
B		PN: -T153-9x/2P => T1S0-9x/P	03.03.2009	RONNY
C		New DWG. No.	01.02.2012	RONNY



PCB LAYOUT TOP VIEW



NOTE

- Material:
Housing: Nylon UL 94V-0
Contact: Phosphor Bronze
Contact plating: Sn over Ni on solder area
Au over Ni on contact area
- Electrical:
Current rating: 1.5A max. @ 25°C
Voltage rating: 150V AC max.
Contact resistance: 15mΩ max.
Dielectric withstanding Voltage:
1000V rms 1 Minute 60Hz
Insulation resistance: 500MΩ min.
- Environmental:
Operating temperature: -20°C to +85°C
Processing temperature: 250°C +/-5°C
for 10 seconds

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-188-T1S0-96/P	6μ"
MJS-188-T1S0-97/P	15μ"
MJS-188-T1S0-98/P	30μ"
MJS-188-T1S0-9H/P	50μ"



UNIT	mm	GENERAL TOLERANCE		DRAWN	Kathy	DATE	21.05.2000	DWG. NO.	1711501	SHEET 1/1
SCALE	Free	X.° ± 5°	X. ± 0.30	CHECK	Ronny	DATE	01.02.2012	SERIES NO.	MJS-1xx-T1S0-9x	REV. C
		.XX° ± 3°	.XX ± 0.25	APPROVE	HOGI	DATE	01.02.2012			
		.XXX° ± 2°	.XX ± 0.15							
		.XXX° ± 1°	.XXX ± 0.10							

SMT PCB JACK SIDE ENTRY
RJ45 <8P8C> unshielded
with straight solder tabs